



Materials



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Category				Description					
				Material Name	Producer	Remark	Standard Materials	Alternative Materials	On Request
Materials	Rigid	Core/Prepreg	FR4 High Tg	MCL-E-679F (J)	Hitachi	high-Temp.	•		
			ВТ ероху	HL832NS HL832NSF	Mitsubishi	packaging substrates	•	•	
			FR4	MCL-E-705G	Hitachi	packaging substrates	•		
			Polyimide glass	MCL-I-671	Hitachi	high-reliability		•	
			High Frequency	HL972LF	Mitsubishi	HF		•	
		Polyimide		Pyralux AC/AP	Du Pont			•	
ate			Adhesiveless	Espanex M-Type	Nippon Steel	standard flex material	•		
PCB Base M				R-F770 / 775	Panasonic	not for military use	•		
				X, W, H-Type	Thinflex			•	
	Flex	Adhesives	Epoxy based	Innoflex	Innox	for advanced SMT assembly		•	
			Acrylic based	Pyralux LF	Du Pont	standard	•		
			High Frequency	undisclosed	undisclosed	HF		•	
			Pressure Sensitive	VHB F9460PC	3M	for stiffener	•		
		FRCC	Flexible Resin Coated Copper	R-FR10	Panasonic	ultrathin Pi with pre applied adhesive		•	
		LCP	Copper clad core	R-F705S	Panasonic	HF, near hermetic		•	
			Bondply	undisclosed	undisclosed	biocompatible		•	
	Constraining Materials			Copper-Invar-Copper		low CTE	•		
				Copper-Molybdenum-C	Copper	heat conductivity		•	
				Copper		heat conductivity			•
Other Materials				Aluminium		heat conductivity			•
			Carbon Copper Core		low CTE, stiff, light weight			•	
	Surface Soldermask		NPR80	Nippon Polytech	flex PCB	•			
			Soldermask	PSR-9000	Taiyo	flex PCB	•		
	Protection Coverfilm			Imagecure	Coates	rigid PCB	•		
			Pyralux LF	Du Pont	flex PCB	•			
	Resistive Foil					74% Ni			
				Inconel	Schlenk	16% Cr			•
					8% Fe				
				ENIG			•		
				ENEPIG			•		

Based in Switzerland, DYCONEX has been in the PCB business for more than 50 years and delivers leading edge interconnect solutions in flex, rigid-flex and rigid technology. DYCONEX core competence lies in the production of highly complex HDI, high-frequency and high-reliability circuit boards for medical, defense, aerospace, industrial and semiconductor applications. DYCONEX is an MST company.

Surface Finishing



0SP

DIG

Electroplated Ni/Au Immersion silver

Biocompatible plated Au



an MST company

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